	<u></u>				
PCN Number:					
Title: Datasheet fo	r OPA211, OPA2211				
Customer Contact:	PCN Manager		De	pt: Quality Services	
Change Type:					
Assembly Site	Desig	ın		Wafer Bump Site	
Assembly Process		Sheet		Wafer Bump Material	
Assembly Material	s Part i	number change		Wafer Bump Process	
Mechanical Specifi				Wafer Fab Site	
Packing/Shipping/	Labeling Test	Process		Wafer Fab Materials	
				Wafer Fab Process	
Notification Details					
Description of Change:					
Texas Instruments Inco	orporated is announcir	ng an information o	only no	otification.	
The product datasheet					
The following change h	istory provides furthe	r details.			
Correction: Datash			I to	J and added corrections	
	fron	n rev J to K.			
√/₄ Ţexas				OBA244 OBA2244	
Instruments		ence	2774 00	OPA211, OPA2211	
		3803	377K-00	CTOBER 2006-REVISED SEPTEMBER 2018	
Changes from Revision J (February 2018) to Revision	K		Page	
_					
	ated errors: "Time" units from				
to "Ω" in <i>Typical Characteristics</i>					
 Corrected system-generated error in unit for resistors from "W" back to "Ω" in Figure 43 Reverted Figure 51 back to that of rev. I 					
- Reverted Figure 51 back	to triat or fev. 1				
Changes from Revision I (lune 2016) to Revision J			Page	
Added "Medical Instrume	ntation" to Applications sectio	n		1	
	• •				
	 Changed product status from mixed product status to production data Deleted Device Comparison table 				
Added NC pin table notes to pin diagrams in the Pin Configurations and Functions section					
Changed formatting of document reference in EMI Rejection section					
Changed formatting of document references in SON Layout Guidelines section					
Changed formatting of document references in SON Layout Guidelines section					
	realite telefolicitees in Aeratee	Documentation section.			
The datasheet number	will be changing				
Device Family	will be changing.	Change From:		Change To:	
Device Fairling		-			
OPA211, OPA2211		SBOS377I		SBOS377K	
These changes may be	reviewed at the datas	sheet links provided	ч.		
,		sileet iiiks providet	u.		
http://www.ti.com/product/OPA211					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
	No anticipated impact. This is a specification change announcement only. There are no changes				
to the actual device.			_		
Changes to product	Changes to product identification resulting from this PCN:				
None					

Product Affected:			
OPA211AID	OPA211AIDR	OPA211ID	OPA211IDRGT
OPA211AIDG4	OPA211AIDRG4	OPA211IDGKR	OPA2211AIDDA
OPA211AIDGKR	OPA211AIDRGR	OPA211IDGKT	OPA2211AIDDAR
OPA211AIDGKT	OPA211AIDRGT	OPA211IDR	OPA2211AIDRGR
OPA211AIDGKTG4	OPA211AIDRGTG4	OPA211IDRGR	OPA2211AIDRGT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com